| Electronic A                         | Electronic Acknowledgement Receipt   |  |  |  |  |  |
|--------------------------------------|--|--|--|--|--|--|
| EFS ID:                              | 9959149  |  |  |  |  |  |
| Application Number:                  |  |  |  |  |  |  |
| International Application Number:    |  |  |  |  |  |  |
| Confirmation Number:                 | 1239   |  |  |  |  |  |
| Title of Invention:                  | SEMICONDUCTOR DEVICE WITH PLASTIC PACKAGE MOLDING COMPOUND SEMICONDUCTOR CHIP AND LEADFRAME AND METHOD FOR PRODUCING THE SAME  Wolfgang Hetzel |  |  |  |  |  |
| First Named Inventor/Applicant Name: |  |  |  |  |  |  |
| Customer Number:                     | 73158  |  |  |  |  |  |
| Filer:                               | Mark L. Gleason/Connie Scheff  |  |  |  |  |  |
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| Application Type:                    | U.S. National Stage under 35 USC 371   |  |  |  |  |  |

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## File Listing:

| Number | Document Description                  | File Name                                    | File Size(Bytes)/<br>Message Digest                   | Multi<br>Part /.zip | Pages<br>(if appl.) |
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| 1      | Response after Ex Parte Quayle Action | SecondResptoExParteQuaylem<br>ailed11911.pdf | 84825<br>7b446ab4bd900f7a54cd0bd28b4cb346d1<br>767e15 | no                  | 4                   |

## **Warnings:**

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| 1 / 1       | Drawings-only black and white line | replacements heet.pdf       | 80754   | no | 1  |
|-------------|------------------------------------|-----------------------------|---|----|----|
|             | drawings                           |                             | <b>bfbd2</b> a33 <b>9d47c</b> 7927bca6f1b61ac329ac98c<br>c140 |    |    |
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### New Applications Under 35 U.S.C. 111

If a new application is being filed and the application includes the necessary components for a filing date (see 37 CFR 1.53(b)-(d) and MPEP 506), a Filing Receipt (37 CFR 1.54) will be issued in due course and the date shown on this Acknowledgement Receipt will establish the filing date of the application.

### National Stage of an International Application under 35 U.S.C. 371

If a timely submission to enter the national stage of an international application is compliant with the conditions of 35 U.S.C. 371 and other applicable requirements a Form PCT/DO/EO/903 indicating acceptance of the application as a national stage submission under 35 U.S.C. 371 will be issued in addition to the Filing Receipt, in due course.

#### New International Application Filed with the USPTO as a Receiving Office

If a new international application is being filed and the international application includes the necessary components for an international filing date (see PCT Article 11 and MPEP 1810), a Notification of the International Application Number and of the International Filing Date (Form PCT/RO/105) will be issued in due course, subject to prescriptions concerning national security, and the date shown on this Acknowledgement Receipt will establish the international filing date of the application.